

EBSO Headquarter in Germany

Over 30 years expierience in electronics

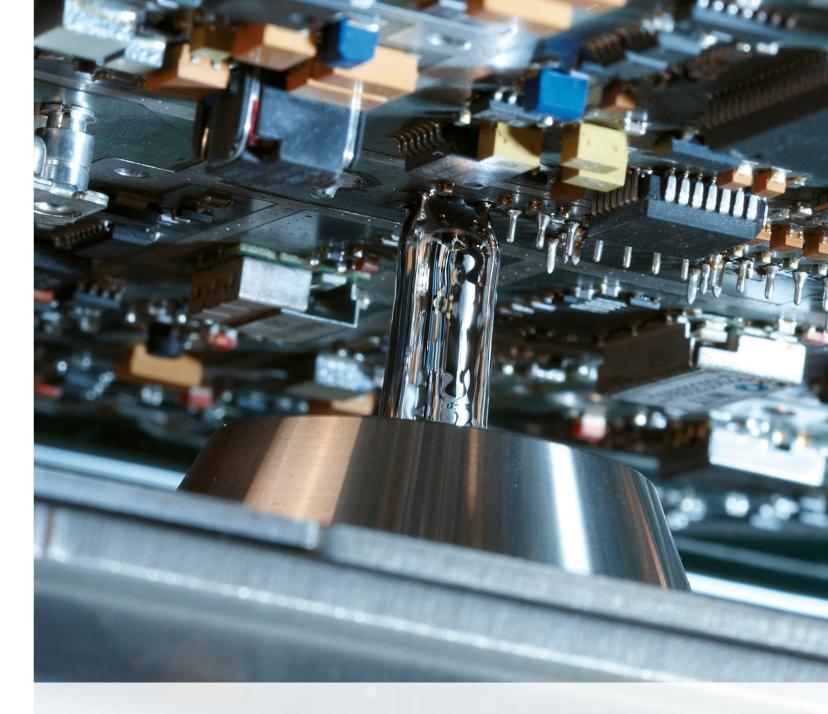


solutions for good connections

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Automatic Selective Soldering Systems





Selective Soldering

with the EBSO SPA Line

Miniwave with overflow wetable solder nozzle





Many components can due to theire thermal sensitivity not be soldered with a traditional wave solder process (LCD displays). Other PCB's are due to SMD component layout issues also can't be soldered successfully using the traditional wave solder process.

Further more often the very costly custom made solder masks to cover the SMD components are difficult to make and not justifiable so customers finish up hand soldering parts. To automate this process the answer is selective soldering.

EBSO already had machines like SPA 300-F and 400-F developed in the year 1999, this machine concept also allows small to medium companies with smaller budgets and production lots to enter this attractive new technology. The SPA Line starts from manual machines all the way up to fully automatic solder centres.

With this particular product line up EBSO has become the world market leader. Product specific solder nozzles and masks round off the enormous know-how EBSO has in this new emerging soldering technology.

Selective soldering makes your THT solder process more efficient and safer due to exact control of flux quantity, preheat and solder temperature. With over 30 well trained distributors world wide, EBSO can provide best service in pre- and aftersales

All SPA machines are built with the same solder pot technology made of fully titanium which is best for lead free solder alloys.

The patented unique "QUICK RELEASE" solder pump is a revolution in terms of maintenance time. This system allows full access to the solder pot within seconds, hence it increases your production efficiency.

"QUICK RELEASE" solder pump

Simply turn pump 45° and the pump is ready







Solder pot with dual nozzle technology and IR-preheat

The EBSO Offline programming software together with the integrated Photo-Editor allows fastest programming times.

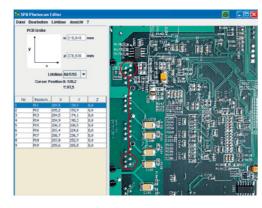


Photo-Editor makes programming easy and comfortable

SPA-R

Rework and Manual Soldering

The bench top machine SPA-R is a manual solder station to rework leaded components such as connectors etc.

Due to RoHS conform electronics the lead free solder temperature raised which made the rework of THT components with a solder iron even more difficult then it was before.

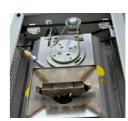
The solution is the SPA-R which makes this process less painless. Furthermore, for manual soldering of small and medium batches the SPA-R can be used as well.



XY-Table with position fixing



Different solder nozzle sizes and customized nozzles



SPA-R insight straightforward engineering



SPA-R with laserpointer to ease component centering over nozzle

Product Highlights:

- Easy to operate
- Timer-function
- Solder pump and solder bath made of fully titanium for lead free solder alloys equipped
- with the "QUICK RELEASE" pump technology
- On the fly wave hight regulation
- Wave standby-function to reduce tack time
- Save of 5 programs
- Easy solder nozzle interchange
- No limits in board size
- Optional N2-supply
- Optional laserpointer to ease component centering over nozzle
- XY-table



Soldering of a connector

SPA 300/400 NC Platform

Etablished worldwide

Since we introduced the SPA 300-F / SPA 400-F to the market in 2003 more then 450 machines has been installed so far.

The concept of the machine allows many options for the requirements of the customers demand. Solder pot as well as solder pump are flood with protective gas. The SPA 300/400 NC platform is designed für the automotive soldering of connector strips, relais, transformers and other conventional assemblies. Especially für applications which aren't qualified for the wave solder process, SPA is ideally applicable to automate the manual soldering process.

The design of the system offers a variety of options and custom specific equipments which could be retrofitted anytime.



Soldering system with charging station

Comforable and fast change via charging station



Processing room of the soldering system

Your advantages:

Integrated, intuitively user interface

EBSO offline editor is a Windows based software to create a solder program for each individual solder joint. It isn't needed any know-how in programming. Additionally, every solder joint can be programmed via an intuitively "point & click"-program. So you'll receive your individual, reproducible soldering program in very short time. Read more about on page 7.

EBSO FAST REMOVE

With the unique EBSO FAST REMOVE pump in the solder pot, you reduce your maintenance time and receive more operational availability.



Soldering process with the wetable nozzle

Die Technologie

3 axis CNC positioning system with Servo drives

FTP interface to Network

Digital Closed Loop control for N2 flow incl. Standby function to reduce

Cost of Ownership

Wave Height control

Autom. Solder wire Feeder and solder level sensor

Flux Tank and flux Level monitoring

Control of all Processparameters

- including monitoring functions
- including maintenance and error messages
- including password protection

Exhaust function monitor

Control lamp freely configurable

Operating state and Maintenance indicator (optional with wireless Net-

work to PC)

Windows CE colour Display

Internal Data management for program storing

Timerfunction

Glashood and Storing compartments

Softwareupdates via USB or CF card

ESD-Paint RAL 7035 (light gray) and RAL 7016 (anthracite

Standard Solder Area Options: 300 x 300 and 400 x 400 mm (15"x15")

All Solderpots made of Titanium

Reliability at highest operational availability due to quick release

solder pump

Easy Change Pot system for lead and lead free production

Single solder pot with just 20 kg Solder capacity

Soldering over 2 Solder pots

Dual Solder nozzle for simultaneous soldering

Max. clearance at solder side 40 mm

Wetable Nozzles 3 – 12 mm Inner Diameter

Jet Nozzles 5 – 60 mm

Wave Nozzle 300 mm

Special nozzles for Dipping process

Max. 4 Fluxers in any combination

Single Spray / Single Microdrop

Dual Spray / Dual Microdrop

Combination of Single or Dual Spray and Microdrop

Convection line Preheater

IR Line or Area Preheater

Top Side IR Preheater

Fluxer Spray test function

Witness colour Camera including TFT Monitor)

AOI for solder control

Barcode or DatamatrixCode with BDA (Traceability)

- Solder Frame identification over RFID-Chip
- including soldering protocol
- including process data recorder

Programming via Offline Editor

- including Photo Editing
- or Import Functions



Production at Werma Signal Lights in Germany: 3 SPA machines, inbetween operator working place insures highest flexibiliy and throughput - always 3 different (or same) products are in production at the same time



Selective soldering application with 45 mm interfering edge

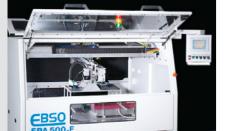


Custom made multi dip nozzle

SPA 500 Modular

Indivudal Solutions for High-end Selective Soldering

The new modular plattform can be equipped for the individual product require-



Unique Technology Advantages:

1 6/ 6

Closed loop XYZ-portal system with servo-drives

Solder angle under 0° and 7° free to program

Max. PCB size 510 x 510 mm

Max. solder mask size 550 x 550 mm

Precise-spray and/or microdrop fluxer for point and line fluxing incl. 2 I flux pot and flux level monitoring

ment in high-end / high-volume selective soldering process.

Titanium solder pot and solder pump - best for lead free

Pump unit equipped with unique "QUICK RELEASE"-design

Solder frame reckognition with integrated collision avoidance

Dual nozzle for simultaneaous soldering to double throughput

Possibility of 4 fluxers (i.e.: 2 drop, 2 spray oder 4 spray fluxer)

2 Flux pots to run 2 differnet fluxers (i.e.: VOC and VOC-free)

Top Site Preheat

Optional Inline

2 solder pots in machine with max. solder area of 510 x 510 mm on both solder pots

i.e.: I solder pot dipping process 2nd solder pot selective miniwave wave

Wide range of solder nozzles and customized such as dipping nozzles

Wetable and jet wave nozzles

N2 inert

Easy change pot option

Saves up to 40 solder programs

Travel speed up to 20 m/min

Process monitoring of

■ Flux level

■ Air and N2 supply

■ Solder level and automatic solder wire feeder

Wave heigh

Easy "point and click" programming with the smart Offline- and Photo-Editor software

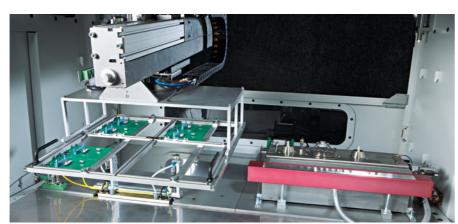
0° or 7°

Top site preheat



SPA-500 as inline with gripper unit





The inside view of the SPA 500

Programming

with the EBSO Offline-Editor

The Ebso offline Editor is a windows based software to create a solder program for each individual solder point. With an easy POINT AND CLICK tool a repeatable solder program is done within minutes

Offline means no programming on the machine

Open fine tune parameter settings for each individual solder joint

Demo mode

Cykle time calculation

Compatible to all EBSO solder machines

Import of Gerber datas or CAD datas possible

Use a CAD Image or a scan of the bare PCB board and click on the position you want to solder. Use the default settings and fine tune in necessary.



| Specific Control of Control of

Use friendliy and intuitve software

Automatic multiplying of panelized boards with bad mark function



Parameter for each single solder joint

Advantages:

- You can consider neighbour SMD components
- Visual orientation on the board while programming
- Solder joint offsets are easier to control
- Program changes can be done quicker

Programming can't be easier

Technical data	SPA 500 Modular	SPA 400-NC	SPA 300-NC	SPA R
l so wh	2000 mm	1600 mm	1300	700 mm
Length			1300 mm	
Width	1950 mm	1200 mm	900 mm	400 mm
Height	1350 mm	1600 mm	1600 mm	250 mm
Weight	500-800 kg	750 kg	450 kg	35kg
Colour	RAL 7035	RAL 7035 and RAL 7016	RAL 7035 and RAL 7016	-
Transportsystem	XYZ axis carrier system	XYZ axis carrier system	XYZ axis carrier system	-
Tarres de la	0° 7° f	0° or 7° fix	0° or 7° fix	
Transportangle	0° or 7° free programmable			-
Max. PCB size	510 x 510 mm	400 x 400 mm	300 x 300 mm	-
Max. frame / fixture size	550 x 550 mm	440 x 440 mm	340 x 340 mm	-
Max. clearance on solder side	30 mm	40 mm	40 mm	-
Max. transportspeed	X axis = 18,5 m/min	X axis = 18 m/min	X axis = 18 m/min	-
	Y axis = 19 m/min	Y axis = 18 m/min	Y axis = 18 m/min	
	Z axis = 10 m/min	Z axis = 18 m/min	Z axis = 18 m/min	
Position accuracy over fluxer,	+ - 0,1 mm with servo drives	+- 0,1 mm with servo drives	+- 0,1 mm with servo drives	-
preheater and solder nozzle	•	,		
Fluxermodule	Optional microdrop-fluxer	Optional microdrop-fluxer	Optional microdrop-fluxer	-
5 .		21	21	-
Flux pot	2 I stainless steel flux pot and fittings incl. flux	2 I stainless steel flux pot and fittings incl. flux	2 I stainless steel flux pot and fittings incl. fux	-
	level monitoring	level monitoring	level monitoring	
Preheater	IR-emmiters	IR-emmiters	IR-emmiters	-
Power	Max 7,5 KW	Max 7,5 KW	Max 7,5 KW	-
Soldermodule	Titanium solder bath and pump	Titanium solder bath and pump	Titanium solder bath and pump	-
Nozzles (refer to data sheet)	let wave nozzle	et wave nozzle	let wave nozzle	-
(Overflow nozzle	Overflow nozzle	Overflow nozzle	_
	Special nozzles	Special nozzles	Special nozzles	_
Smallest nozzle diameter	2.5 mm on overflow nozzles	2.5 mm on overflow nozzles	2.5 mm on overflow nozzles	_
Sitialiest Hozzle diameter	4,0 mm on jet wave nozzles	4,0 mm on jet wave nozzles	4,0 mm on jet wave nozzles	_
M::				-
Min. neighbour component clearance	1,5-3 mm (depends on nozzle type)	1,5-3 mm (depends on nozzle type)	1,5-3 mm (depends on nozzle type)	-
Solder capacity	Approx. 35 kg	Approx. 35 kg	Approx. 35 kg	-
Max. temperature	400°C	350℃	350°C	-
Upheat time	Approx. 35 minutes	Approx. 30 - 45 min. depends on the soldier bath	Approx. 30 - 45 min. depends on the soldier bath	350°C
Solder time	free programmable	free programmable	free programmable	-
Nitrogen technology				-
N2	by user (bottles, tank, generator are suitable)	by user (bottles, tank, generator are suitable)	by user (bottles, tank, generator are suitable)	optional
Preasure	2 bar	2 bar	2 bar	2 bar / I-3 m³ adjustable
Consumption	1,5-3 m ³ /h adjustable	1,5-3 m ³ /h adjustable	1,5-3 m ³ /h adjustable	-
N2 type	2.7 or 99,9 %	from 2.7 or 99,9%	from 2.7 or 99,9%	-
Inline	Standard SMEMA with conveyor and gripper	-	_	_
Air	orania or izi i/ with convo/or and gripper			
Pressure	6 bar			
SPS	Siemens S7-200 SPS	Schleicher CNC control with Windows CE	Schleicher CNC control with Windows CE	
3F3				-
A	incl. touch-screen panel	colour touch-screen panel	colour touch-screen panel	-
Automatic timer				-
Working hours counter				-
Maintenance control				-
Password protection				-
Manual Operation	Wave height, fluxer, preheat,	Wave height, fluxer, preheat,	Wave height, fluxer, preheat,	-
	solder temperature	solder temperature	solder temperature	-
Electrical data				
Power	3 x 230 / 400 V, N, PE 50 / 60 Hz	3 x 230 / 400 V, N, PE 50 / 60 Hz	3 x 230 / 400 V, N, PE 50 / 60 Hz	-
Power tolerance range	+6%, -10%	+6%, -10%	+6%, -10%	-
Power consumption	Max. 15 KW	Max. 7,5 KW - 5 KW depends on configuration	Max. 7,5 KW - 5 KW depends on configuration	-
Fuse rate	Max. 3 x 25 A	Max. 3 x 16 A - 3 x 25 A depends on configuration	Max. 3 x 16 A - 3 x 25 A depends on configuration	-
Exhaust			•	
Exhaust power	150 m³/h	150 m³/h	150 m³/h	-
Extension tube	Ø 100 mm	Ø 100 mm	Ø 100 mm	-
Enviroment temperature	15-30°C	15-30°C	15-30°C	-
Permanent sound level	< 50 dB	< 50 dB	< 50 dB	_
Further			. 55 45	
Welded iron frame	<u> </u>	_	_	_
vveided if off if affle			•	-







Lead Forming



Since more than 30 years the cutting and forming of THT components is the core business of EBSO.

With over 20 standard preforming machines we can provide solutions to any kind of lead forming jobs.

Despite of the SMT technology, THT components are still in use in reasonable quantities in the electronic industry hence makes a big portion of our business.

Visit our website to learn more about EBSO products.







System integration and custom automized systems

Individual customized automation solutions, which often challenging requirements, are part of the engineering services EBSO provides. No matter if it is a complete turnkey solution, special conditioning or a economically and technically implemented system integration.



We plan, design, manufacture and assemble customized solutions. Trust in our 30 years experience. Numerous successfully implemented projects in the automotive, consumer, telecommunications, electrical, electronics and ceramic industry speak for themselves.

Process Monitoring

You always have a reliable partner at your side

We assist our customers before, but also during and after the integration of our solutions in their production. Our goal is to install a zero defect process. A claim, which we pursue in the interests of our clients without any compromise.





References

BERU AG	• KUHNKE	• SANMINA SCI
• BOSCH	 MARQUARDT 	• SIEMENS
• FABRINET	• MENTOR	• STIEBEL ELTRON
• FESTO	• MIELE	• STILL
• GRUNDIG	• MOTOROLA	• VALEO
• HONEYWELL	• MSC	• WERMA
• HOMAG	• OSRAM	• ZF
• KOSTAL	• OTIS	• ZOLLNER